

Title (en)

Composition for preparing organic insulator

Title (de)

Zusammensetzung zur Darstellung eines organischen Insulators

Title (fr)

Composition pour la préparation d'un isolateur organique

Publication

EP 1524299 A1 20050420 (EN)

Application

EP 04256183 A 20041006

Priority

KR 20030071775 A 20031015

Abstract (en)

Disclosed is a composition for preparing an organic insulator, the composition comprising (i) at least one organic-inorganic hybrid material; (ii) at least one organometallic compound and/or organic polymer; and (iii) at least one solvent for dissolving the above two components, so that an organic insulator using the same has a low threshold voltage and driving voltage, and high charge carrier mobility and Ion/Ioff ratio, thereby enhancing insulator characteristics. Further, the preparation of organic insulating film can be carried out by wet process, so that simplification of the process and cut of cost are achieved. <IMAGE>

IPC 1-7

C08L 83/06; H01L 21/3205; H01L 21/316

IPC 8 full level

H01L 21/31 (2006.01); **C08G 77/04** (2006.01); **C08K 5/05** (2006.01); **C08L 83/04** (2006.01); **C08L 83/06** (2006.01); **C08L 101/00** (2006.01); **C09D 5/25** (2006.01); **C09D 183/04** (2006.01); **C09D 183/06** (2006.01); **H01L 21/312** (2006.01); **H01L 21/316** (2006.01); **H01L 21/3205** (2006.01); **H01L 29/786** (2006.01); **H01L 51/05** (2006.01); **H01L 51/30** (2006.01); **H01L 51/40** (2006.01); **C08K 5/057** (2006.01); **C08K 5/56** (2006.01)

CPC (source: EP KR US)

C08L 83/04 (2013.01 - EP US); **C09D 183/06** (2013.01 - EP US); **H01B 3/18** (2013.01 - EP US); **H01L 21/02126** (2013.01 - US); **H01L 21/02172** (2013.01 - EP US); **H01L 21/02186** (2013.01 - US); **H01L 21/02282** (2013.01 - US); **H01L 21/31** (2013.01 - KR); **H10K 10/478** (2023.02 - EP US); **C08G 77/04** (2013.01 - EP US); **C08K 5/057** (2013.01 - EP US); **C08K 5/56** (2013.01 - EP US); **H01L 21/02126** (2013.01 - EP); **H01L 21/02186** (2013.01 - EP); **H01L 21/02216** (2013.01 - EP); **H01L 21/02282** (2013.01 - EP); **H01L 21/3122** (2013.01 - US); **H10K 85/615** (2023.02 - EP US); **Y10T 428/31504** (2015.04 - EP US); **Y10T 428/31663** (2015.04 - EP US)

C-Set (source: EP US)

C08L 83/04 + **C08L 2666/02**

Citation (search report)

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Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

US 2005259212 A1 20051124; **US 8017245 B2 20110913**; CN 1607685 A 20050420; CN 1607685 B 20120229; DE 602004027980 D1 20100819; EP 1524299 A1 20050420; EP 1524299 B1 20100707; JP 2005120371 A 20050512; JP 4562027 B2 20101013; KR 101012950 B1 20110208; KR 20050036171 A 20050420; US 2006147715 A1 20060706

DOCDB simple family (application)

US 12830905 A 20050513; CN 200410088162 A 20041014; DE 602004027980 T 20041006; EP 04256183 A 20041006; JP 2004294415 A 20041007; KR 20030071775 A 20031015; US 80727104 A 20040324